THC63LVDF84B

LVDS 24Bit COLOR HOST-LCD PANEL INTERFACE RECEIVER (Falling Edge Clock)

General Description

The THC63LVDF84B receiver supports wide VCC range(2.5~3.6V). At single 2.5V supply, the THC63LVDF84B reduces EMI and power consumption.

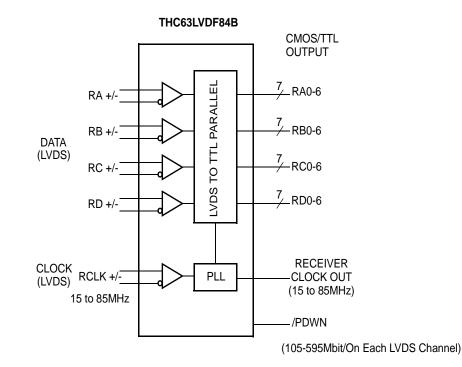
The THC63LVDF84B receiver convert the four LVDS (Low Voltage Differential Signaling) data streams back into 24bits of CMOS/TTL data with falling edge clock. At a transmit clock frequency of 85MHz, 24bits of RGB data and 4bits of LCD timing and control data (HSYNC, VSYNC, CNTL1, CNTL2) are transmitted at a rate of 2.3Gbps.

Features

		Clock Frequency[MHz]				
vCC[v]	15 to 20	20 to 70	70 to 85			
2.5 to 2.7	n/a	available	n/a			
2.7 to 3.0	available	available	n/a			
3.0 to 3.6	available	available	available			
n/a : not available						

- Wide dot clock and Wide VCC range:
- Falling Edge Clock
- PLL requires No external components
- Rx power consumption < 80mW @VCC 2.5V, 65MHz Grayscale
- Power-Down Mode
- Low profile 56 Lead TSSOP Package
- Pin compatible with THC63LVDF84A

Block Diagram



Pin Out

RC3 <u>1</u> RD6 <u>2</u> RC4 <u>3</u> GND <u>4</u> RC5 <u>5</u> RC6 <u>6</u> RD0 <u>8</u> RA- <u>10</u> RA+ <u>10</u> RB+ <u>11</u> LVDSGND <u>8</u> RA+ <u>10</u> RB+ <u>12</u> LVDSVCC <u>14</u> RC+ <u>15</u> RC+ <u>16</u> RCLK+ <u>17</u> RCLK+ <u>18</u> RD+ <u>19</u> RD+ <u>20</u> LVDSGND <u>21</u> PLLGND <u>22</u> PLLVCC <u>23</u> PLLQND <u>24</u> /PDWN <u>25</u> CLKOUT <u>26</u> RA0 <u>27</u> GND <u>28</u>	56 VCC 55 RC2 54 RC1 53 RC0 51 RB6 50 RD4 49 RD4 47 RB5 48 VCC 47 RB5 46 RB4 45 RD2 41 RD2 41 RD2 41 RD2 39 RB1 38 RB0 37 RA6 36 GND 35 RA4 32 RA3 31 VCC 30 RA2 31 VCC2 32 RA1
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THC63LVDF84B

Pin Description

Pin Name	Pin #	Туре	Description
RA+, RA-	10, 9	LVDS IN	
RB+, RB-	12, 11	LVDS IN	LVDS Data Inputs
RC+, RC-	16, 15	LVDS IN	
RD+, RD-	20, 19	LVDS IN	
RCLK+, RCLK-	18, 17	LVDS IN	LVDS Clock Inputs
RA0~RA6	27,29,30,32,33,35,37	OUT	
RB0~RB6	38,39,43,45,46,47,51	OUT	Pixel Date Outpute
RC0~RC6	53,54,55,1,3,5,6	OUT	Pixel Data Outputs
RD0~RD6	7,34,41,42,49,50,2	OUT	
CLKOUT	26	OUT	Pixel Clock Output
/PDWN	25	IN	H: Normal operation
	20	IIN	L: Power down (all outputs are pulled to ground)
VCC	31,40,48,56	Power	Power Supply Pins for TTL outputs and digital circuitry
GND	4,28,36,44,52	Ground	Ground Pins for TTL outputs and digital circuitry
LVDSVCC	13	Power	Power Supply Pin for LVDS inputs
LVDSGND	8,14,21	Ground	Ground Pins for LVDS inputs
PLLVCC	23	Power	Power Supply Pin for PLL circuitry
PLLGND	22,24	Ground	Ground Pins for PLL circuitry

Absolute Maximum Ratings_

Supply Voltage (V _{CC})	-0.3V ~ +4.0V
CMOS/TTL Input Voltage	-0.3V ~ (V _{CC} + 0.3V)
CMOS/TTL Output Voltage	$-0.3V \sim (V_{CC} + 0.3V)$
LVDS Receiver Input Voltage	-0.3V ~ (V _{CC} + 0.3V)
Junction Temperature	+125°C
Storage Temperature Range	-55°C ~ +150°C
Reflow Peak Temperature / Time	+260°C / 10sec.
Maximum Power Dissipation @+25°C	1.9W

Recommended Operating Conditions

Parameter		Min.	Max.	Units
All Supply Voltage		2.5	3.6	V
Operating Ambi	Operating Ambient Temperature		70	°C
	VCC=2.5V to 2.7V	20	70	MHz
Clock Frequency	VCC=2.7V to 3.0V	15	70	MHz
	VCC=3.0V to 3.6V	15	85	MHz

Electrical Characteristics

CMOS/TTL DC SPECIFICATIONS

	100 - 100 - 1100 -					- 2000
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V _{IH}	High Level Input Voltage		2.0		VCC	V
V _{IL}	Low Level Input Voltage		GND		0.8	V
V _{OH1}	High Level Output Voltage	VCC= 3.0V ~ 3.6V I _{OH} = -4mA	2.4			V
V _{OL1}	Low Level Output Voltage	VCC = 3.0V ~ 3.6V I _{OL} = 4mA			0.4	V
V _{OH2}	High Level Output Voltage	VCC= 2.5V ~ 3.0V I _{OH} = -2mA	2.1			V
V _{OL2}	Low Level Output Voltage	$VCC = 2.5V \sim 3.0V$ $I_{OL} = 2mA$			0.4	V
I _{IN}	Input Current	$0V \le VIN \le VCC$			±10	μΑ

Vcc = VCC = PVCC = LVCC

LVDS RECEIVER DC SPECIFICATIONS

Vcc = VCC = PVCC = LVCC

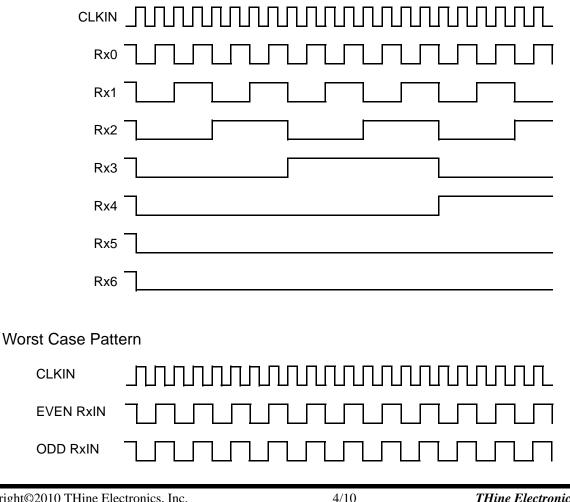
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V _{TH}	Differential Input High Threshold	VIC = +1.2V			100	mV
V _{TL}	Differential Input Low Threshold	VIC = +1.2V	-100			mV
lu,	Input Current	$V_{IN} = +2.4 V/0 V$			±10	μA
IIN		VCC = 3.6V			<u> </u>	μΛ

Supply Current

Vcc = VCC = PVCC = LVCC

Symbol	Parameter	Condition(*)		Тур.	Max.	Units
	Receiver Supply Current	CL=8pF, VCC=3.3V	f = 65MHz	41	53	mA
I _{RCCG}	,	CL=0PF, VCC=3.3V	f = 85MHz	52	64	mA
	16Grayscale Pattern	CL=8pF, VCC=2.5V	f = 65MHz	30	42	mA
	Pagaivar Supply Current	t CL=8pF, VCC=3.3V	f = 65MHz	72	94	mA
I _{RCCW}	Receiver Supply Current Worst Case Pattern		f = 85MHz	84	96	mA
Worst Case Pattern	WOIST Case Fallen	CL=8pF, VCC=2.5V	f = 65MHz	42	64	mA
I _{RCCS}	Receiver Power Down Supply Current	/PDWN = L			10	μΑ

16 Gray Scale Pattern



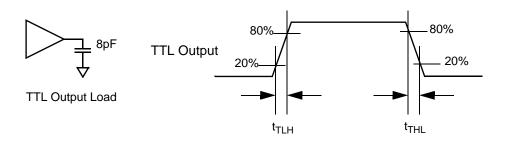
Switching Characteristics

Vcc = VCC = PVCC = LVCC

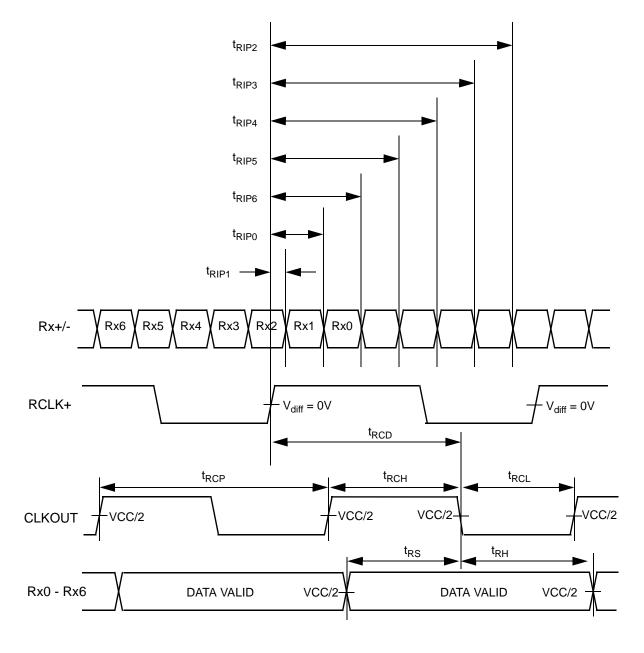
Symbol	Paran	neter	Min.	Тур.	Max.	Units
		VCC = 2.5 - 2.7V	14.3	Т	50.0	ns
t _{RCP}	CLK OUT Period	VCC = 2.7 - 3.0V	14.3	Т	66.6	ns
		VCC = 3.0 - 3.6V	11.8	Т	66.6	ns
t _{RCH}	CLK OUT High Time			4T/7		ns
t _{RCL}	CLK OUT Low Time			3T/7		ns
t _{RCD}	RCLK +/- to CLK OUT	Delay		5T/7		ns
t _{RS}	TTL Data Setup to CL	K OUT	0.35T-0.3			ns
t _{RH}	TTL Data Hold from C	KL OUT	0.45T-1.6			ns
t _{TLH}	TTL Low to High Tran	sition Time		2.0	3.0	ns
t _{THL}	TTL High to Low Tran	sition Time		1.8	3.0	ns
t _{RIP1}	Input Data Position0 (T = 11.76ns)	-0.4	0.0	0.4	ns
t _{RIP0}	Input Data Position1 (T = 11.76ns)	T/7-0.4	T/7	T/7+0.4	ns
t _{RIP6}	Input Data Position2 (T = 11.76ns)	2T/7-0.4	2T/7	2T/7+0.4	ns
t _{RIP5}	Input Data Position3 (T = 11.76ns)	3T/7-0.4	3T/7	3T/7+0.4	ns
t _{RIP4}	Input Data Position4 (T = 11.76ns)	4T/7-0.4	4T/7	4T/7+0.4	ns
t _{RIP3}	Input Data Position5 (T = 11.76ns)	5T/7-0.4	5T/7	5T/7+0.4	ns
t _{RIP2}	Input Data Position6 (T = 11.76ns)	6T/7-0.4	6T/7	6T/7+0.4	ns
t _{RPLL}	Phase Lock Loop Set				10.0	ms

AC Timing Diagrams

TTL Output



AC Timing Diagrams

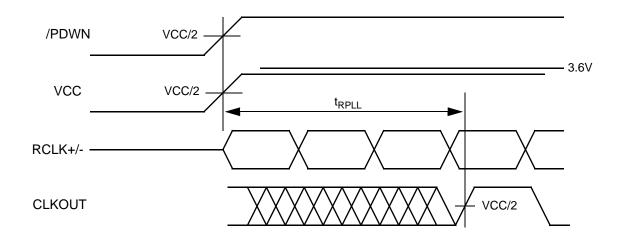


Note: 1) Vdiff = (RA+) - (RA-), (RCLK+) - (RCLK-)

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AC Timing Diagrams

Phase Lock Loop Set Time





Note

1)Power On Sequence Power on LVDS-Tx after THC63LVDF84B.

2)Cable Connection and Disconnection

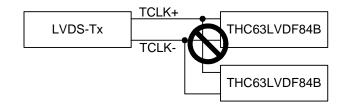
Don't connect and disconnect the LVDS cable, when the power is supplied to the system.

3)GND Connection

Connect the each GND of the PCB which LVDS-Tx and THC63LVDF84B on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

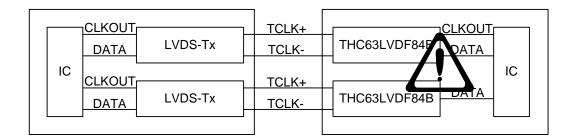
4)Multi Drop Connection

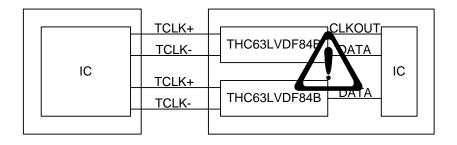
Multi drop connection is not recommended.



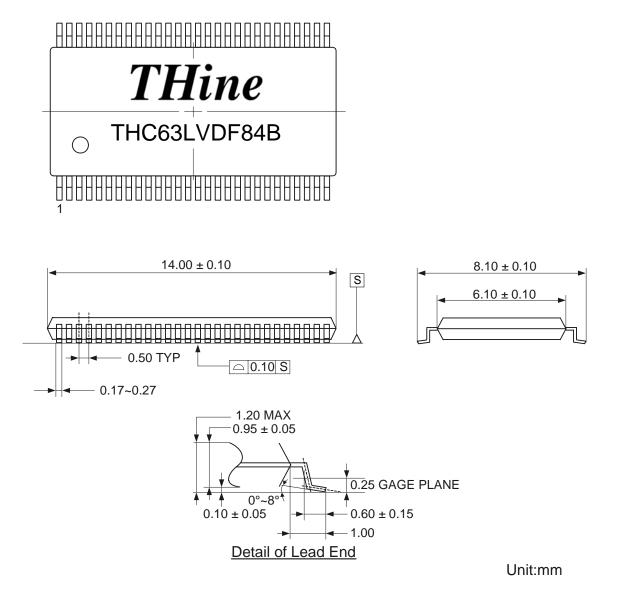
5)Asynchronous use

Asynchronous use such as following systems are not recommended.





Package



Notices and Requests

- 1. The product specifications described in this material are subject to change without prior notice.
- 2. The circuit diagrams described in this material are examples of the application which may not always apply to the customer's design. We are not responsible for possible errors and omissions in this material. Please note if errors or omissions should be found in this material, we may not be able to correct them immediately.
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